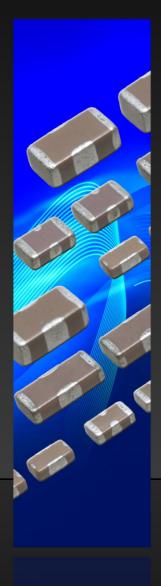


MULTILAYER CERAMIC CHIP CAPACITORS



CKD Series Low ESL Feed Through Type

Type: CKD110JB

CKD310JB CKD510JB CKD610JB CKD61BJB

Issue date: April 2011

TDK MLCC US Catalog

Version B11

REMINDERS

Please read before using this product

SAFETY REMINDERS



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CKD Series







Low ESL Feed Through Type

Type: CKD610JB (C1608), CKD510JB (C2012), CKD110JB (C3212), CKD310JB (C3216), CKD61BJB (C1608)

Features



- · These small low-cost filters are used for meeting EMC requirements
- · Can be used at higher frequencies due to low parasitic inductance
- · Optimized for use as a noise bypass capacitor for signal and power source circuits

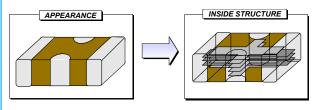
Applications

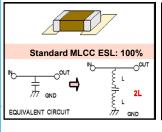


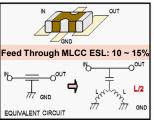
- · Decoupling CPU power line
- · High speed digital IC/decoupling
- · High impedance/high current circuits
- DC to DC converter input/output smoothing
- · Power supply

Structure



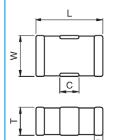






Shape & **Dimensions**







Body Width **Body Height** GND Terminal Width

Terminal Width

Dimensions in mm

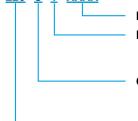


CKD510JB 0J 226 S T XXXX

¢	Series Name			
٠	Jenies Maine			
	Case Code	Length	Width	
	CKD610JB	1.60 ± 0.10	0.80 ± 0.10	
	CKD510JB	2.00 ± 0.20	1.25 ± 0.20	
	CKD110JB	3.20 ± 0.20	1.25 ± 0.20	
	CKD310JB	3.20 ± 0.20	1.60 ± 0.20	_
	CKD61BJB	1.60 ± 0.10	0.80 ± 0.10	

Rated Voltage (DC)

Voltage Code	Voltage (DC)
0J	6.3V
1A	10V
1C	16V
1E	25V
1H	50V



Internal Codes

Packaging Style

Packaging Code	Style
T	Tape & Reel

Capacitance Tolerance

Tolerance Code	Tolerance	
S	+50/-20%	_

Nominal Capacitance (pF)

The capacitance is expressed in three digit codes and in units of pico Farads (pF). The first and second digits identify the first and second significant figures of the capacitance. The third digit identifies the multiplier. R designates a decimal point.

Capacitance Code	Capacitance
0R5	0.5pF
010	1pF
102	1,000pF (1nF)
105	1,000,000pF (1µF)





CKD610JB [EIA CC0603]

Capacitance Range Chart

Rated Voltage: 6.3V (0J)

Capacitance (pF)	Cap Code	Tolerance	0J (6.3V)
470,000	474	S: +50/-20%	
1,000,000	105		
2,200,000	225		
4,700,000	475		
10,000,000	106		

Standard Thickness 0.80 mm



Capacitance Range Table

CKD610JB [EIA CC0603]

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (I _{dc} max)	DC Resistance (max)
CKD610JB0J105S	6.3V	1,000,000	+50/-20%	0.80 ± 0.10	2,000 mA	12 m Ω
CKD610JB0J225S	6.3V	2,200,000	+50/-20%	0.80 ± 0.10	2,000 mA	12 m Ω
CKD610JB0J475S	6.3V	4,700,000	+50/-20%	0.80 ± 0.10	2,000 mA	12 mΩ



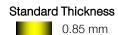


CKD510JB [EIA CC0805]

Capacitance Range Chart

Rated Voltage: 50V (1H), 25V (1E), 16V (1C), 10V (1A), 6.3V (0J)

Capacitance (pF)	Cap Code	Tolerance	1H (50V)	1E (25V)	1C (16V)	1A (10V)	0J (6.3V)
22	220	S: +50/-20%					
47	470						
100	101						
220	221						
470	471						
1,000	102						
2,200	222						
4,700	472						
10,000	103						
22,000	223						
47,000	473						
100,000	104						
470,000	474						
1,000,000	105						
2,200,000	225						
4,700,000	475						
10,000,000	106						
22,000,000	226						





Capacitance Range Table

CKD510JB [EIA CC0805]

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (I _{dc} max)	DC Resistance (max)
CKD510JB1H220S	50V	22	+50/-20%	0.85 ± 0.15	400 mA	500 mΩ
CKD510JB1H470S	50V	47	+50/-20%	0.85 ± 0.15	400 mA	500 mΩ
CKD510JB1H101S	50V	100	+50/-20%	0.85 ± 0.15	400 mA	500 mΩ
CKD510JB1H221S	50V	220	+50/-20%	0.85 ± 0.15	400 mA	500 mΩ
CKD510JB1H471S	50V	470	+50/-20%	0.85 ± 0.15	400 mA	500 mΩ
CKD510JB1H102S	50V	1,000	+50/-20%	0.85 ± 0.15	400 mA	500 mΩ
CKD510JB1H222S	50V	2,200	+50/-20%	0.85 ± 0.15	400 mA	500 mΩ
CKD510JB1H472S	50V	4,700	+50/-20%	0.85 ± 0.15	400 mA	500 mΩ
CKD510JB1E103S	25V	10,000	+50/-20%	0.85 ± 0.15	1,000 mA	80 mΩ
CKD510JB1E223S	25V	22,000	+50/-20%	0.85 ± 0.15	1,000 mA	80 mΩ
CKD510JB1E473S	25V	47,000	+50/-20%	0.85 ± 0.15	1,000 mA	80 mΩ
CKD510JB1E104S	25V	100,000	+50/-20%	0.85 ± 0.15	1,000 mA	80 mΩ
CKD510JB1C474S	16V	470,000	+50/-20%	0.85 ± 0.15	2,000 mA	30 mΩ
CKD510JB1A105S	10V	1,000,000	+50/-20%	0.85 ± 0.15	2,000 mA	12 mΩ
CKD510JB1A225S	10V	2,200,000	+50/-20%	0.85 ± 0.15	2,000 mA	12 mΩ
CKD510JB1A475S	10V	4,700,000	+50/-20%	0.85 ± 0.15	3,000 mA	12 mΩ
CKD510JB0J106S	6.3V	10,000,000	+50/-20%	0.85 ± 0.15	4,000 mA	5 mΩ
CKD510JB0J226S	6.3V	22,000,000	+50/-20%	0.85 ± 0.15	4,000 mA	5 mΩ





CKD110JB [EIA CC1205]

Capacitance Range Chart

Rated Voltage: 25V (1E)

Hated Voltage. 20V (TL)										
Capacitance (pF)	Cap Code	Tolerance	1E (25V)							
22	220	S: +50/-20%								
47	470									
100	101									
220	221									
470	471									
1,000	102									
2,200	222									
4,700	472									
10,000	103									
22,000	223									
47,000	473									
100,000	104									

Standard Thickness
0.85 mm



Capacitance Range Table

CKD110JB [EIA CC1205]

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (I _{dc} max)	DC Resistance (max)
CKD110JB1E220S	25V	22	+50/-20%	0.85 ± 0.15	200 mA	600 mΩ
CKD110JB1E470S	25V	47	+50/-20%	0.85 ± 0.15	200 mA	600 mΩ
CKD110JB1E101S	25V	100	+50/-20%	0.85 ± 0.15	200 mA	600 mΩ
CKD110JB1E221S	25V	220	+50/-20%	0.85 ± 0.15	200 mA	$600~\text{m}\Omega$
CKD110JB1E471S	25V	470	+50/-20%	0.85 ± 0.15	200 mA	600 mΩ
CKD110JB1E102S	25V	1,000	+50/-20%	0.85 ± 0.15	200 mA	600 mΩ
CKD110JB1E222S	25V	2,200	+50/-20%	0.85 ± 0.15	200 mA	600 mΩ
CKD110JB1E472S	25V	4,700	+50/-20%	0.85 ± 0.15	200 mA	600 mΩ
CKD110JB1E103S	25V	10,000	+50/-20%	0.85 ± 0.15	500 mA	300 mΩ
CKD110JB1E223S	25V	22,000	+50/-20%	0.85 ± 0.15	500 mA	300 mΩ
CKD110JB1E473S	25V	47,000	+50/-20%	0.85 ± 0.15	500 mA	300 mΩ
CKD110JB1E104S	25V	100,000	+50/-20%	0.85 ± 0.15	500 mA	300 mΩ





CKD310JB [EIA CC1206]

Capacitance Range Chart

Rated Voltage: 16V (1C), 6.3V (0J)

Capacitance (pF)	Cap Code	Tolerance	(1C (16V)	0J (6.3V)
100,000	104	S: +50/-20%			
220,000	224				
470,000	474				
1,000,000	105				
22,000,000	226				

Standard Thickness
1.30 mm



Capacitance Range Table

CKD310JB [EIA CC1206]

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (I _{dc} max)	DC Resistance (max)
CKD310JB1C104S	16V	100,000	+50/-20%	1.30 ± 0.15	2,000 mA	40 m Ω
CKD310JB1C224S	16V	220,000	+50/-20%	1.30 ± 0.15	2,000 mA	40 mΩ
CKD310JB1C474S	16V	470,000	+50/-20%	1.30 ± 0.15	2,000 mA	40 mΩ
CKD310JB1C105S	16V	1,000,000	+50/-20%	1.30 ± 0.15	2,000 mA	40 mΩ
CKD310JB0J226S	6.3V	22,000000	+50/-20%	1.30 ± 0.15	4,000 mA	12 mΩ





CKD61BJB [EIA CC0603]

Capacitance Range Chart

Rated Voltage: 6.3V (0J)

. O.OV (00)	
Cap Code	Tolerance	0J (6.3V)
104	S: +50/-20%	
474		
105		
475		
106		
	Cap Code 104 474 105 475	Tolerance 104 474 105 475

Standard Thickness
0.60 mm



Capacitance Range Table

CKD61BJB [EIA CC0603]

TDK Part Number (Ordering Code)	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)	Rated Current (I _{dc} max)	DC Resistance (max)
CKD61BJB0J474S	6.3V	470,000	+50/-20%	0.60 ± 0.10	2,000 mA	$30~\text{m}\Omega$
CKD61BJB0J105S	6.3V	1,000,000	+50/-20%	0.60 ± 0.10	2,000 mA	30 m Ω
CKD61BJB0J475S	6.3V	22,000000	+50/-20%	0.60 ± 0.10	2,000 mA	12 mΩ



No.	Item	Performance	Test or Inspection Method
1	External Appearance	No defects which may affect performance.	Inspect with magnifying glass (3 $ imes$).
2	Insulation Resistance	10,000M Ω or 500M Ω •μF min., whichever smaller (As for the capacitors of rated voltage 16, 10, 6.3V DC, 100M Ω •μF min.).	Apply rated voltage for 60s.
3	Direct Current Resistance R _{dc (1-2)}	R_{dc} is between $5M\Omega$ - $600~M\Omega$ depending on item. See the Capacitance Range Chart section to obtain item specific parameters.	Measuring current should be 100mA max. ${}^{3}{\rm R}_{{\rm m}\Omega{\rm max}{\rm dc}{\rm II}}$ ${}^{4}{\rm R}_{\rm dc}{\rm II}$
4	Voltage Proof	Withstand test voltage without insulation breakdown or other damage.	2.5 x rated voltage (DC) shall be applied for 1 to 5s Charge / discharge current shall not exceed 50mA.
5	Capacitance	Within the specified tolerance.	Measuring Frequency Measuring Voltage
			1kHz±10% 0.5 - 5 V _{rms} 1.0±0.2V _{rms}
6	Dissipation Factor (D.F.)	10% maximum	See No.5 in this table for measuring condition.
7	Bending	No mechanical damage.	Reflow solder the capacitor on P.C. board (shown in Appendix 2, Appendix 4 or Appendix 6) and bend 1 mm.
8	Solderability	New solder to cover over 75% of termination.	Completely soak both terminations in solder at 235 \pm 5°C for 2 \pm 0.5s.
		25% may have pin holes or rough spots but not concentrated in one spot. Ceramic surface of "A sections" shall not be exposed due to melting or shifting of termination material.	Solder: H63A (JIS Z 3282) Flux: Isopropyl alcohol (JIS K 8839) Rosin (JIS K 5902) 25% solid solution.





No.	Item	Performance	Test o	r Inspection Method	
9	Resistance to so	older heat No mechanical damage.	260±5	etely soak both terminations °C for 5±1s. ting condition	in solder at
	Capacitance	Change from the value before test	— Ten	np.: 150±10°C e: 1 to 2min.	
		± 7.5%		opropyl alcohol (JIS K 8839) osin (JIS K 5902) 25% solid	
	D.F. (Class 2)	Meet the initial spec.		H63A (JIS Z 3282)	
	Insulation Resistance	Meet the initial spec.		he capacitor in ambient con measurement.	ditions for 24 \pm 2h
	Voltage Proof	No insulation breakdown or other damage.			
	Resistance for DC (R _{dc})	1.0 Ω max.	_		
10	Temperature cyc	cle		solder the capacitor on P.C.	•
	External appearance	No mechanical damage.	Expose	lix 1 or Appendix 3) before to the capacitor in the condition	ons step1 through
	Capacitance	Change from the value before test	Leave t	and repeat 5 times consecut he capacitor in ambient con	•
		± 7.5%		measurement.	Time of (mains)
	D.F. (Class 2)	Meet the initial spec.	— <u>Step</u> 1	Temperature (°C) Min. operating temp. ±3	Time (min.)
	Insulation	Meet the initial spec.		20 ± 2	2-5
	Resistance	meet are initial open.	3	Max. operating temp. \pm 2	30 ± 2
	Resistance for DC (R _{dc})	1.0 Ω max.	4	20 ± 2	2 - 5
11		ance (Steady State)	Reflow	solder the capacitors on P.0	C. board (shown ir
	External appearance	No mechanical damage.	Append	lix 1 or Appendix 3) before to at temperature 40±2°C, 90	esting.
	Capacitance	Change from the value before test		he capacitor in ambient con	ditions for 24±2h
		± 12.5%	before r	measurement.	
	D.F. (Class 2)	200% of initial spec. max.	_		
	Insulation Resistance	1,000MΩ or $50M\Omega \cdot \mu F$ min, whichever smaller. (As for the capacitors of rated voltage 16, 10, 6.3V DC, $10M\Omega \cdot \mu F$ min.)	_		
	Resistance for DC (R _{dc})	1.0 Ω max.			

MULTILAYER CERAMIC CHIP CAPACITORS



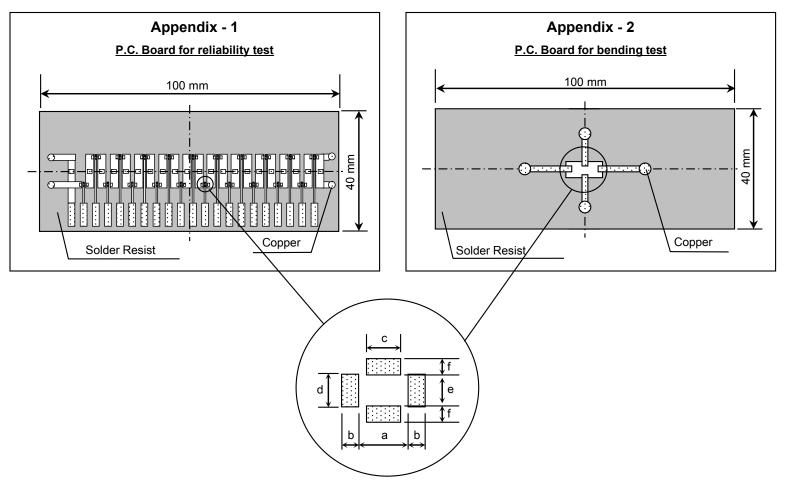
CKD Series – Feed Through Type

No.	Item	Performance	Test or Inspection Method
12	Life		Reflow solder the capacitor on P.C. board (shown in Appendix 1, Appendix 3 or Appendix 5) before testing.
	External appearance	No mechanical damage.	Voltage shall be applied at maximum operating temperature ±2°C for 1,000 +48, 0h.
	Capacitance	Change from the value before test	Applied voltage is 1xRV; however some items may be tested at higher voltage (1.2x, 1.5x or 2xRV).
		± 15%	Charge/discharge current shall not exceed 50mA.
	D.F. (Class 2)	200% of initial spec. max.	Leave the capacitor in ambient conditions for 24±2h before measurement.
	Insulation Resistance	1,000M Ω or 50M Ω •μF min., whichever smaller. (As for the capacitors of rated voltage 16, 10, 6.3V DC, 10M Ω •μF min.)	Voltage conditioning: Voltage treats the capacitor under testing temperature and voltage for 1 hour.
	Resistance for DC (R _{dc})	1.0 Ω max.	Leave the capacitor in ambient conditions for 24 \pm 2h before measurement.
			Use this measurement for initial value.

^{*}As for the initial measurement of capacitors on number 9, 10 and 11, leave capacitors at 150 –10, 0°C for 1 hour and measure the value after leaving capacitors for 24±2h in ambient condition.







Appendix - 1 & 2

	Case Code				Dimension	ons (mm)		
Series	JIS	EIA	а	b	С	d	е	f
CKD710JB	C1005	CC0402	0.7	0.3	0.19	0.6	0.25	0.25

Material: Glass Epoxy (As per JIS C6484 GE4)

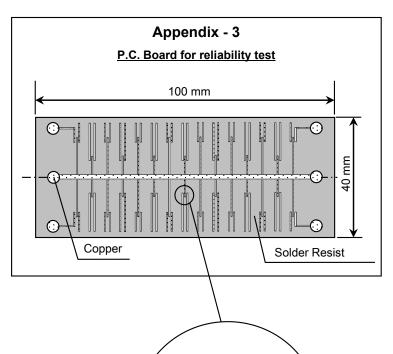
P.C. Board thickness: 1.6mm

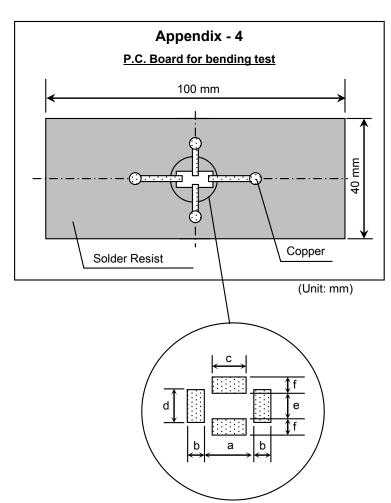
Copper (thickness 0.035mm)

Solder resist









Appendix - 3

	Case Code				Dimensio	ons (mm)		
Series	JIS	EIA	а	b	С	d	е	f
CKD610JB	C1608	CC0603	1.0	0.6	0.4	0.6	0.4	0.4

Appendix - 4

	Case Code			Dimensi	ons (mm)	
Series	JIS	EIA	а	b	С	d
CKD610JB	C1608	CC0603	0.4	0.5	0.4	2.0

Material: Glass Epoxy (As per JIS C6484 GE4)

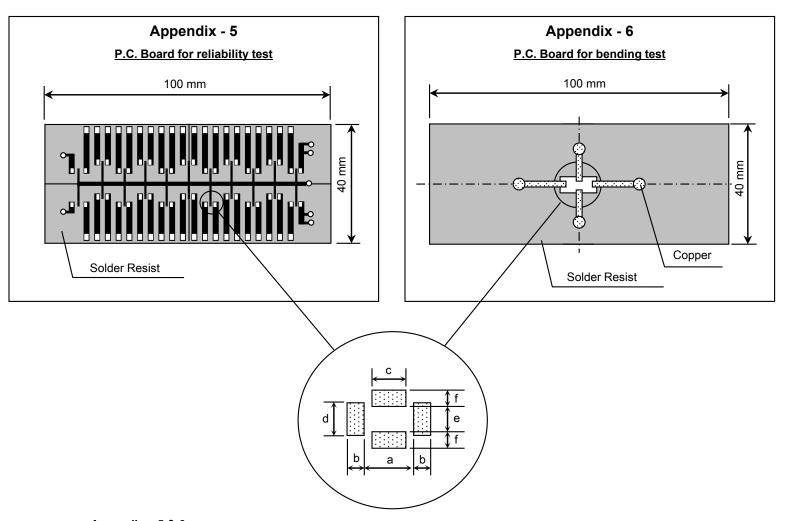
P.C. Board thickness: 1.6mm

Copper (thickness 0.035mm)

Solder resist







Appendix - 5 & 6

	Case Code				Dimension	ons (mm)		
Series	JIS	EIA	а	b	С	d	е	f
CKD510JB	C2012	CC0805	1.4	0.6	0.5	0.8	0.6	0.65
CKD110JB	C3212	CC1205	2.5	0.7	1.4	1.0	0.6	0.7
CKD310JB	C3216	CC1206	2.5	1.2	1.4	1.3	0.8	0.9

Material: Glass Epoxy (As per JIS C6484 GE4)

P.C. Board thickness: 1.6mm

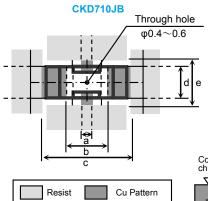
Copper (thickness 0.035mm)

Solder resist





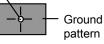
Recommended Soldering Land Pattern



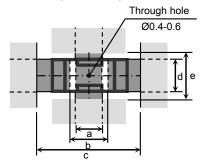
Back side:

Back side shall be connected to the ground pattern of the chip mounted side. Please design the back side ground as large as possible.

Connect to the ground pattern of the chip mounted side.

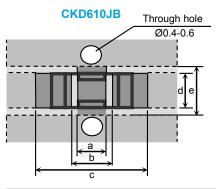


CKD510JB, CKD110JB, CKD310JB



*If through hole is too big, solder paste may come into the hole and make bad connection with the ground pattern.

Symbol Series	а	b	С	d	е
CKD710JB	0.19	0.7	1.3	0.6	0.75
CKD510JB	0.5	1.5	2.6	1.0	2.0
CKD110JB	1.4	2.5	4.5	1.0	2.0
CKD310JB	1.4	2.5	4.5	1.2	2.4



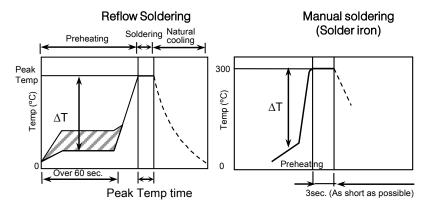
Connect to the ground pattern of the chip mounted side.

"Through hole" should be designed as close to GND terminal as possible.

|--|

Symbol Series	а	b	С	d	е
CKD610JB	0.4	1.2	2.2	0.7	1.4

Recommended Soldering Profile



Recommended soldering duration

Temp./	Reflow Soldering			
Dura. Solder	Peak temp (°C)	Duration (sec.)		
Sn-Pb Solder	230 max.	20 max.		
Lead-Free Solder	260 max.	10 max.		

Recommended solder compositions

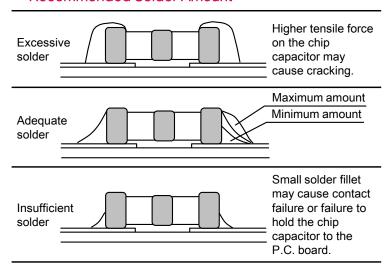
Sn-37Pb (Sn-Pb solder)

Sn-3.0Ag-0.5Cu (Lead Free Solder)

Preheating Condition

Soldering Method	Temperature (°C)		
Reflow soldering	ΔT ≤ 150		
Manual soldering	ΔT ≤ 150		

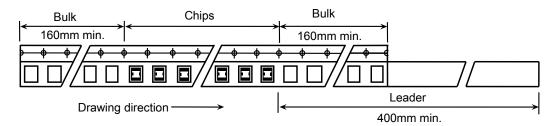
Recommended Solder Amount



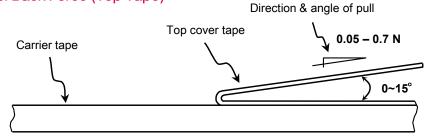




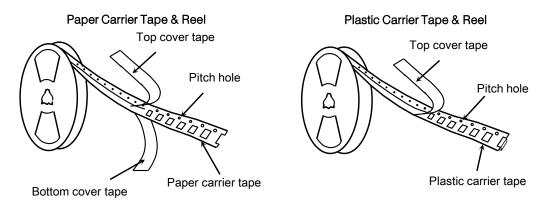
Carrier Tape Configuration



• Peel Back Force (Top Tape)



- Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.
- The missing of components shall be less than 0.1%
- · Components shall not stick to the cover tape.
- The cover tape shall not protrude beyond the edges of the carrier tape not shall cover the sprocket holes.
- Chip Quantity Per Reel and Structure of Reel (Paper & Plastic)

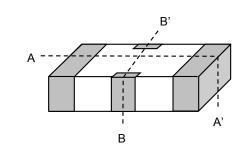


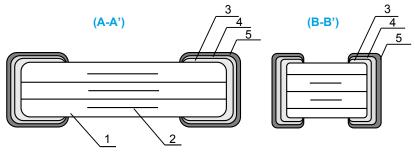
Case Code			Chip	Tanina	Chip quantity (pcs.)		
Series	JIS	EIA	Thickness (mm)	Taping Material	φ178mm (7") reel	φ330mm (13") reel	
CKD710JB	C1005	CC0402	0.30		10,000	50,000	
CKD610JB	C1608	CC0603	0.80				
CKD510JB	C2012	CC0805	0.85	Paper	4,000	40.000	
CKD110JB	C3212	CC1205	0.85			10,000	
CKD310JB	C3216	CC1206	1.30	Plastic	2.000	1	





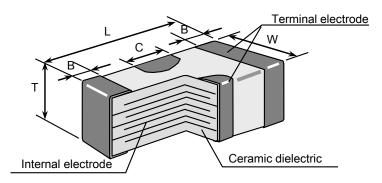
Inside Structure & Material System





No.	NAME	MATERIAL
NO.	INAIVIE	WATERIAL
(1)	Ceramic Dielectric	CaZrO ₃ or BaTiO ₃
(2)	Internal Electrode	Nickel (Ni)
(3)		Copper (Cu)
(4)	Termination	Nickel (Ni)
(5)		Tin (Sn)

Shape & Dimensions



Case Code			Dimensions (mm)				
Series	JIS	EIA	L	W	Т	В	С
CKD710JB	C1005	CC0402	1.00	0.55	0.30	0.17	0.30
CKD610JB	C1608	CC0603	1.60	0.80	0.80	0.10	0.40
CKD510JB	C2012	CC0805	2.00	1.25	0.85	0.30	0.40
CKD110JB	C3212	CC1205	3.20	1.25	0.85	0.40	0.95
CKD310JB	C3216	CC1206	3.20	1.60	1.30	0.40	0.95

Environmental Information

TDK Corporation established internal product environmental assurance standards that include the six hazardous substances banned by the EU RoHS Directive¹ enforced on July 1, 2006 along with additional substances independently banned by TDK and has successfully completed making general purpose electronic components conform to the RoHS Directive².

- Abbreviation for Restriction on Hazardous Substances, which refers to the regulation EU Directive 2002/95/EC on hazardous substances by the European Union (EU) effective from July 1, 2006. The Directive bans the use of six specific hazardous substances in electric and electronic devices and products handled within the EU. The six substances are lead, mercury, cadmium, hexavalent chromium, PBB (polybrominated biphenyls), and PBDE (polybrominated diphenyl ethers).
- This means that, in conformity with the EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.

For REACH (SVHC: 15 substances according to ECHA / October 2008): All TDK MLCC do not contain these 15 substances.

For European Directive 2000/53/CE and 2005/673/CE :
Cadmium, Hexavalent Chromium, Mercury, Lead are
not contained in all TDK MLCC.

For European Directive 2003/11/CE: Pentabromodiphenylether, Octabromodiphenylether are not contained in all TDK MLCC.